

TMMDB3TG

Datasheet

Diac in MINIMELF package with tight V_{BO}



MINIMELF

Features

- V_{BO}: 32 V
- Low breakover voltage: 15 µA max.
- Breakover voltage range: 30 to 34 V

Applications

- General purpose AC line load switching
- Motor control circuits
- Home appliances
- Heating
- Lighting
- Inrush current limiting circuits
- Overvoltage crowbar protection

Description

Functioning as a trigger diode with a fixed voltage reference, the TMMDB3TG can be used in conjunction with Triacs for simplified gate control circuits or as a starting element in fluorescent lamp ballasts.

Product status link		
TMMDB3TG		
Product summary		
Order code	V _{BO}	
TMMDB3TG	30 - 34 V	

1 Characteristics

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Table 1. Absolute maximum ratings (limiting values), T_j = 25 °C unless otherwise specified

Symbol	Parameter	Value	Unit
I _{TRM}	Repetitive peak on-state current, t_p = 20 µs, F = 120 Hz	2	А
T _{stg}	Storage junction temperature range -40 to +125		°C
Tj	Operating junction temperature range		°C

Table 2. Electrical characteristics (T_j = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions		Value	Unit
			Min.	30	
V _{BO}	Breakover voltage ⁽¹⁾	C = 10 nF ⁽²⁾	Тур.	32	V
			Max.	34	
I V _{BO1} - V _{BO2} I	Breakover voltage symmetry	C = 10 nF ⁽²⁾	Max.	2	V
ΔV	Dynamic breakover voltage ⁽¹⁾	V_{BO} and V_{F} at 10 mA	Min.	9	V
V _O	Output voltage ⁽¹⁾	See Figure 2. Test circuit , (R = 20 Ω)	Min.	5	V
I _{BO}	Breakover current ⁽¹⁾	C = 10 nF ⁽²⁾	Max.	15	μA
t _r	Rise time ⁽¹⁾	See Figure 3. Rise time measurement	Max.	2	μs
I _R	Leakage current ⁽¹⁾	V _R = 0.5 x V _{BO} max	Max.	10	μA
lp	Peak current ⁽¹⁾	See Figure 2. Test circuit	Min.	0.30	Α

1. Applicable to both forward and reverse directions.

2. Connected in parallel to the device

Figure 1. Voltage - current characteristic curve.

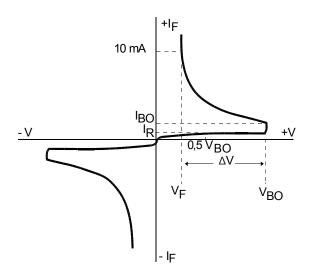


Figure 2. Test circuit

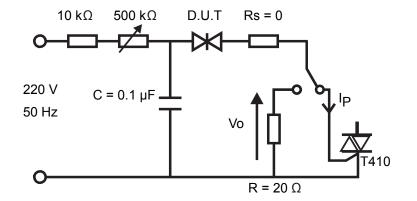
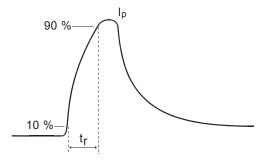


Figure 3. Rise time measurement



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1.1 Characteristics (curves)

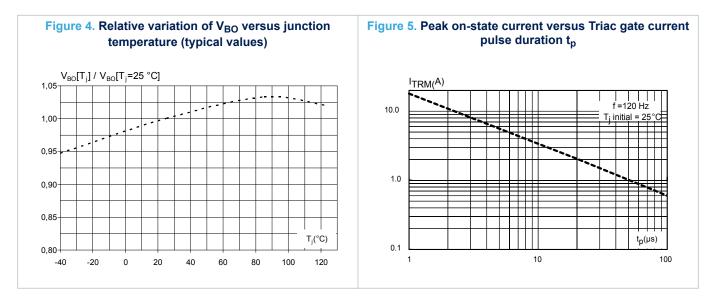
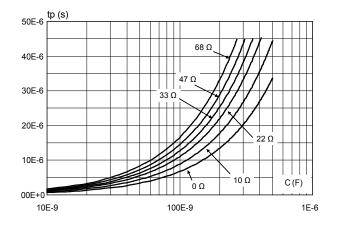


Figure 6. Triac gate current pulse duration t_p (to have $I_P > 50$ mA) versus Rs and C values (typical values)



Note: according to Figure 2. Test circuit

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 Minimelf package information

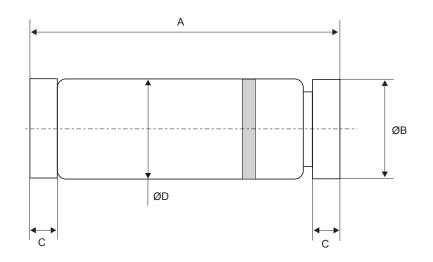


Figure 7. MINIMELF package outline

Table 3. MINIMELF package mechanical data

Dim	Dim			mm		
Dim.	Min.	Тур.	Max.	Min.	Тур.	Max.
A	3.30	3.50	3.70	0.130	0.138	0.146
В	1.59	1.65	1.70	0.063	0.065	0.067
С	0.40	0.50	0.60	0.016	0.020	0.024
D		1.50			0.059	



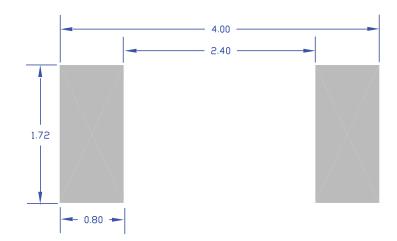


Figure 8. MINIMELF recommended footprint (dimensions are in mm)

3 Ordering information

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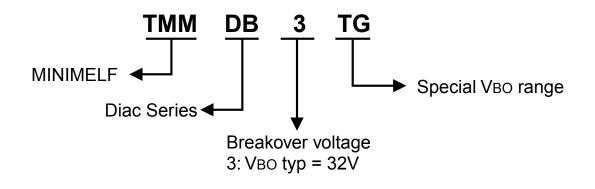


Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
TMMDB3TG	(None)	Minimelf	0.04 g	2500	Tape and reel

Revision history

Table 5.	Document	revision	history
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Date	Version	Changes
January-2001	2	Previous release.
07-May-2019	3	Updated Section 1.1 Characteristics (curves) and Table 3. MINIMELF package mechanical data. Minor text change to improve readability.



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